

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

TSSOP Exp. Pad

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**TOTAL MASS (g) : 0.097468**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004611	1000000	47307.6640625		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.030596	975000	313907		
		Iron (Fe)	7439-89-6	0.000753	24000	7725.58447266		
		Phosphorus (P)	7723-14-0	0.000009	300	92.3376617432		
		Zinc (Zn)	7440-66-6	0.000022	700	225.714294434		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.031380</b>	<b>1000000</b>	<b>321950.6875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002480	1000000	25447.7871094		
		<b>External Plating Total:</b>				<b>0.002480</b>	<b>1000000</b>	<b>25447.7871094</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000806	1000000	8269.35058594		
<b>Internal Plating Total:</b>				<b>0.000806</b>	<b>1000000</b>	<b>8269.35058594</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001241	750000	12732.3378906		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000414	250000	4247.53271484		
<b>Die Attach Total:</b>				<b>0.001655</b>	<b>1000000</b>	<b>16979.8710938</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.007460	135000	76537.6640625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.047524	860000	487583.90625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000276	5000	2831.68847656		
		<b>Encapsulation Total:</b>				<b>0.055260</b>	<b>1000000</b>	<b>566953.25</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001276	1000000	13091.4287109		
					<b>TOTAL MASS (g) :</b>	<b>0.097468</b>		